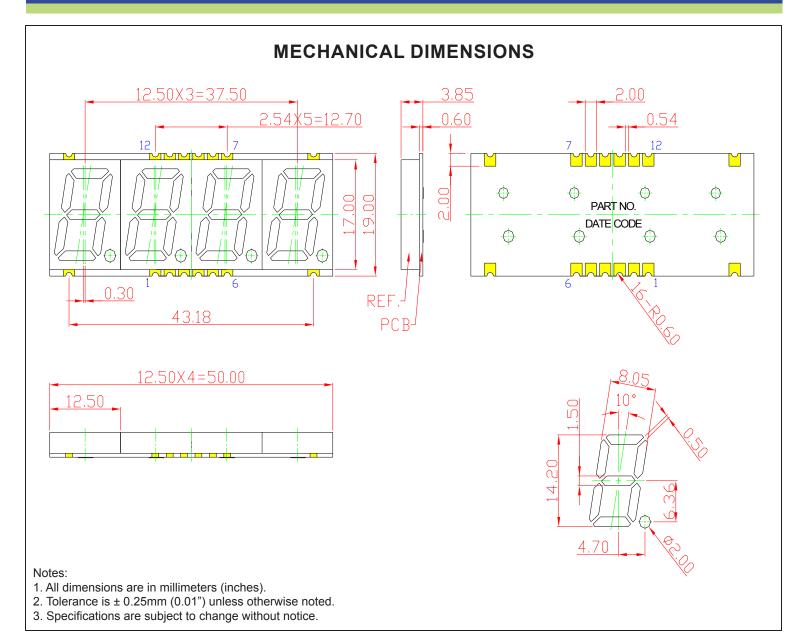


# SPECIFICATIONS SDQA56GT2W

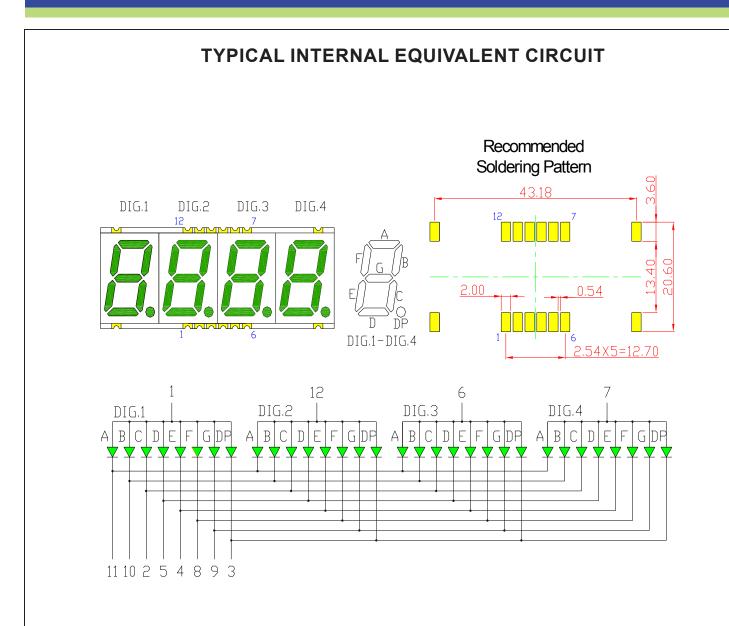


Part Number	Chip Material	Color of Emission	Lens Type	Description	
SDQA56GT2W	InGaN	Green	White Segment	Common Anode	





### **SPECIFICATIONS**



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm$  0.25mm (0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.





### **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol		Unit
Power Dissipation per Dice	Pad	120	mW
Derating Liner from 25°C per Dice	-	0.3	mA / °C
Continuous Forward Current per Dice	laf	30	mA
Peak Current per Dice (duty cycle 1/10, 1kHz)	lpf	100	mA
Reverse Voltage per Dice	VR	5	°C
Operating Temperature	Topr	-40~+105	°C
Storage Temperature	Тѕтс	-40~+105	°C

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

Characteristic	Symbol	Condition	Value			Lloit
Characteristic			Min.	Type.	Max.	Unit
Forward Voltage per Dice	VF	IF =20mA	-	3.2	4.0	V
Reverse Current per Dice	lR	VR = 5V	-	-	10	μΑ
Peak Wavelength per Dice	λР	IF =20mA	-	530	-	nm
Dominant Wavelength per Dice	λD	IF =20mA	-	525	-	nm
Luminous Intensity	lv	IF =20mA	-	90	-	mcd
Spectral Radiation Bandwidth per Dice	Δλ	IF =20mA	-	30	-	nm

<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.





### **OPTICAL CHARACTERISTIC CURVES**

### (25 °C Free Air Temperature Unless Otherwise Specified)

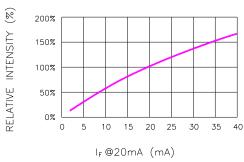


Fig. 1 RELATIVE INTENSITY VS. FORWARD CURRENT

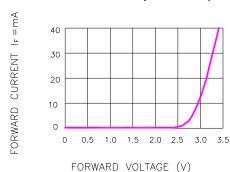
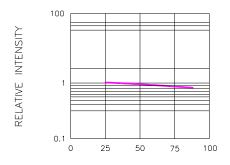
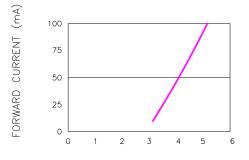


Fig.2 FORWARD CURRENT VS. FORWARD VOLTAGE



LEAD TEMPERATURE(\*C)
Fig.3 RELATIVE INTENSITY VS.LEAD TEMPERATURE
(PULSED 20 mA; 300us
PULSE,10ms PERIOD)



FORWARD VOLTAGE(V)

Fig.4 PEAK FORWARD VOLTAGE

VS.FORWARD(100us TEST PULSE,

1% DUTY CYCLE)

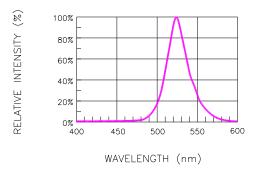
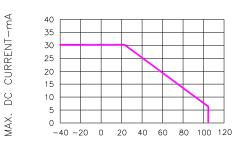


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH



AMBIENT TEMPERATURE (TA)-°C

Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE



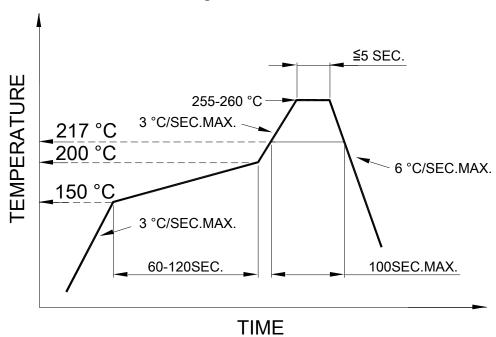


### **SOLDERING CONDITIONS - SMD TYPE LED**

#### RECOMMEND SOLDERING PROFILE

SMT Soldering Profile

Pb free reflow soldering Profile



### SOLDERING IRON

Basic specification : ≦4 seconds when 260°C, If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

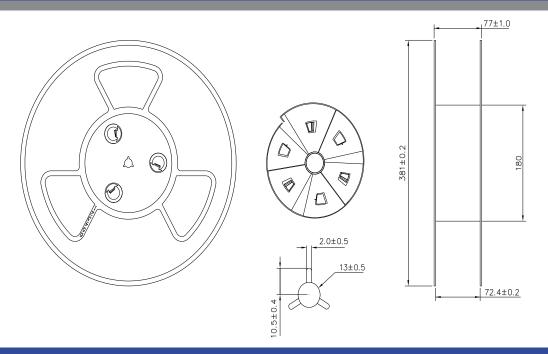
### REWORK

Customer must finish rework within ≦3 sec under 350°C.





# **DIMENSIONS OF TAPE (Unit: mm)**



### **PACKAGING SPECIFICATION**

